16-/32-Channel, 4 Ω, +1.8 V to +5.5 V and ±2.5 V Analog Multiplexers

Data Sheet

ADG726/ADG732

FEATURES

- 1.8 V to 5.5 V single-supply operation
- ±2.5 V dual-supply operation
- On resistance: 4 Ω at 25°C (+5 V single supply/±2.5 V dual supply)
- 0.5 Ω on-resistance flatness at 25°C (+5 V single supply/±2.5 V dual supply)
- Rail-to-rail operation
- Transition times: 23 ns typical at 25°C
- Single 32-to-1 channel multiplexer
- Dual/differential 16-to-1 channel multiplexer
- TTL-/CMOS-compatible inputs
- 48-lead TQFP or 48-lead, 7 mm × 7 mm LFCSP

APPLICATIONS

- Optical applications
- Data acquisition systems
- Communication systems
- Relay replacement
- Audio and video switching
- Battery-powered systems
- Medical instrumentation
- Automatic test equipment (ATE)

FUNCTIONAL BLOCK DIAGRAMS

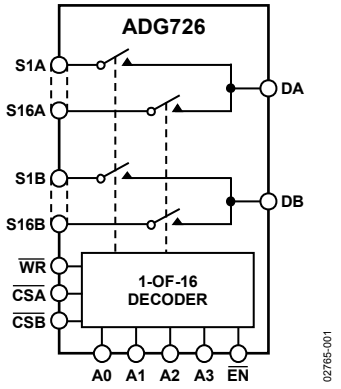


Figure 1.

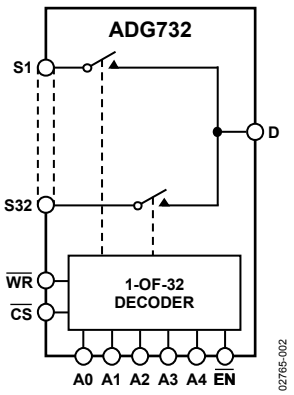


Figure 2.

GENERAL DESCRIPTION

The ADG726/ADG732 are monolithic, complementary metal oxide semiconductor (CMOS) 32-channel and dual 16-channel analog multiplexers. The ADG732 switches one of 32 inputs (S1 to S32) to a common output, D, as determined by the 5-bit binary address lines A0, A1, A2, A3, and A4. The ADG726 switches one of 16 inputs as determined by the 4-bit binary address lines A0, A1, A2, and A3.

On-chip latches facilitate microprocessor interfacing. The ADG726 may also be configured for differential operation by tying $\overline{CSA}$ and $\overline{CSB}$ together. An $\overline{EN}$ input is used to enable or disable the devices. When disabled, all channels are switched off.

These multiplexers are designed on an enhanced submicron process that provides low power dissipation yet gives high switching speed, very low on resistance, and leakage currents. They operate from a single supply of +1.8 V to +5.5 V and a ±2.5 V dual supply, making them ideally suited to a variety of applications. On resistance is in the region of a few ohms and is closely matched between switches and very flat over the full signal range. These devices can operate equally well as either multiplexers or demultiplexers and have an input signal range that extends to the supplies. In the off condition, signal levels up to the supplies are blocked. All channels exhibit break-before-make switching action, preventing momentary shorting when switching channels.

The ADG726/ADG732 are available in a 48-lead LFCSP or a 48-lead TQFP. For functionally equivalent devices with serial interface, see the ADG725/ADG731.

PRODUCT HIGHLIGHTS

1. +1.8 V to +5.5 V single- or ±2.5 V dual-supply operation. These devices are specified and guaranteed with +5 V ± 10%, +3 V ± 10% single-supply, and ±2.5 V ± 10% dual-supply rails.
2. An on resistance of 4 Ω.
3. Guaranteed break-before-make switching action.
4. 48-lead LFCSP package or 48-lead TQFP package.

Rev. A

One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A.
Tel: 781.329.4700
Technical Support www.analog.com

TABLE OF CONTENTS

REVISION HISTORY

2/15—Rev. 0 to Rev. A

Updated Format ..... Universal
Changes to Features Section 1
Changes to Table 1 3
Changes to Table 2 5
Changes to Table 3 7
Changes to Table 5 9
Added Table 6; Renumbered Sequentially 10
Added Table 7 11
Changes to Figure 5 11
Changes to Figure 8 to Figure 11 13
Changes to Figure 13 and Figure 15 to Figure 17 14
Changes to Figure 25 to Figure 28 16
Changes to Figure 29 17
Moved Terminology Section 18
Changes to Terminology Section 18
Updated Outline Dimensions 19
Changes to Ordering Guide 19

7/02—Revision 0: Initial Version

SPECIFICATIONS

+5 V SINGLE SUPPLY

V_{DD} = 5 V ± 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.

Table 1.

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range			0 V to V_{DD}		V	
On Resistance	R_{ON}	4	5		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA, see Figure 18
		5.5	6	7	Ω max	
On Resistance Match Between Channels	ΔR_{ON}		0.3		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
			0.8	1	Ω max	
On Resistance Flatness	$R_{FLAT (ON)}$	0.5			Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
			1	1.2	Ω max	
LEAKAGE CURRENTS						V_{DD} = 5.5 V
Source Off Leakage	I_S (Off)	±0.01			nA typ	V_D = 4.5 V/1 V, V_S = 1 V/4.5 V, see Figure 19
		±0.25	±1	±2	nA max	
Drain Off Leakage	I_D (Off)	±0.05			nA typ	V_D = 4.5 V/1 V, V_S = 1 V/4.5 V, see Figure 22
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
Channel On Leakage	I_D, I_S (On)	±0.05			nA typ	V_D = V_S = 1 V, or 4.5 V, see Figure 23
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
DIGITAL INPUTS						
Input High Voltage	V_{INH}		2.4	2.4	V min	
Input Low Voltage	V_{INL}		0.8	0.8	V max	
Input Current						
Low or High	I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.5	±0.5	μA max	
Digital Input Capacitance	C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS[1]						
Transition Time	$t_{TRANSITION}$	23			ns typ	R_L = 300 Ω, C_L = 35 pF, see Figure 25
		34	40	48	ns max	V_{S1} = 3 V/0 V, V_{S32} = 0 V/3 V
Break-Before-Make Time Delay	t_D	18			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 3 V, see Figure 26
			1	1	ns min	
On Time ($\overline{CS}$, $\overline{WR}$)	t_{ON} ($\overline{CS}$, $\overline{WR}$)	18			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 3 V, see Figure 27
		25	32	38.5	ns max	
Off Time ($\overline{CS}$, $\overline{WR}$)	t_{OFF} ($\overline{CS}$, $\overline{WR}$)	17			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 3 V, see Figure 27
		23	29	33	ns max	
On Time ($\overline{EN}$)	t_{ON} ($\overline{EN}$)	24			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 3 V, see Figure 28
		32	40	43	ns max	
Off Time ($\overline{EN}$)	t_{OFF} ($\overline{EN}$)	16			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 3 V, see Figure 28
		22	25	25	ns max	
Charge Injection	Q_{INJ}	5			pC typ	V_S = 2.5 V, R_S = 0 Ω, C_L = 1 nF, see Figure 29
Off Isolation	I_{SO}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 20
Channel-to-Channel Crosstalk	C_{TK}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 21
−3 dB Bandwidth	BW					R_L = 50 Ω, C_L = 5 pF, see Figure 24
ADG726		34			MHz typ	
ADG732		18			MHz typ	

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
Off Switch Source Capacitance	C_S (Off)	13			pF typ	f = 1 MHz
Off Switch Drain Capacitance	C_D (Off)					
ADG726		170			pF typ	f = 1 MHz
ADG732		340			pF typ	f = 1 MHz
On Switch Drain, Source Capacitance	C_D, C_S (On)					
ADG726		175			pF typ	f = 1 MHz
ADG732		350			pF typ	f = 1 MHz
POWER REQUIREMENTS						V_{DD} = 5.5 V
Positive Supply Current	I_{DD}	10			µA typ	Digital inputs = 0 V or 5.5 V
			20	20	µA max	

[1] Guaranteed by design; not subject to production test.

+3 V SINGLE SUPPLY

V_{DD} = 3 V ± 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.

Table 2.

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range			0 V to V_{DD}		V	
On Resistance	R_{ON}	7			Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA, see Figure 18
		11	12	13	Ω max	
On Resistance Match Between Channels	ΔR_{ON}		0.35		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
			1	1	Ω max	
On Resistance Flatness	$R_{FLAT (ON)}$		3		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
LEAKAGE CURRENTS						V_{DD} = 3.3 V
Source Off Leakage	I_S (Off)	±0.01			nA typ	V_S = 3 V/1 V, V_D = 1 V/3 V, see Figure 19
		±0.25	±1	±2	nA max	
Drain Off Leakage	I_D (Off)	±0.05			nA typ	V_S = 1 V/3 V, V_D = 3 V/1 V, see Figure 22
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
Channel On Leakage	I_D, I_S (On)	±0.05			nA typ	V_S = V_D = 1 V or 3 V, see Figure 23
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
DIGITAL INPUTS						
Input High Voltage	V_{INH}		2.0	2.0	V min	
Input Low Voltage	V_{INL}		0.7	0.7	V max	
Input Current						
Low or High	I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.5	±0.5	μA max	
Digital Input Capacitance	C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS[1]						
Transition Time	$t_{TRANSITION}$	34			ns typ	R_L = 300 Ω, C_L = 35 pF, see Figure 25
		52	62	69	ns max	V_{S1} = 2 V/0 V, V_{S32} = 0 V/2 V
Break-Before-Make Time Delay	t_D	26			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 2 V, see Figure 26
			1	1	ns min	
On Time ($\overline{CS}$, $\overline{WR}$)	t_{ON} ($\overline{WR}$, $\overline{CS}$)	29			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 2 V, see Figure 27
		43	52	60	ns max	
Off Time ($\overline{CS}$, $\overline{WR}$)	t_{OFF} ($\overline{WR}$, $\overline{CS}$)	26			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 2 V, see Figure 27
		38	42	55.5	ns max	
On Time ($\overline{EN}$)	t_{ON} ($\overline{EN}$)	33			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 2 V, see Figure 28
		48	55	63.5	ns max	
Off Time ($\overline{EN}$)	t_{OFF} ($\overline{EN}$)	19			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 2 V, see Figure 28
		25	28	28	ns max	
Charge Injection	Q_{INJ}	1			pC typ	V_S = 1.5 V, R_S = 0 Ω, C_L = 1 nF, see Figure 29
Off Isolation	I_{SO}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 20
Channel-to-Channel Crosstalk	C_{TK}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 21
−3 dB Bandwidth	BW					R_L = 50 Ω, C_L = 5 pF, see Figure 24
ADG726		34			MHz typ	
ADG732		18			MHz typ	

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
Off Switch Source Capacitance	C_S (Off)	13			pF typ	f = 1 MHz
Off Switch Drain Capacitance	C_D (Off)					
ADG726		170			pF typ	f = 1 MHz
ADG732		340			pF typ	f = 1 MHz
On Switch Drain, Source Capacitance	C_D, C_S (On)					
ADG726		175			pF typ	f = 1 MHz
ADG732		350			pF typ	f = 1 MHz
POWER REQUIREMENTS						V_{DD} = 3.3 V
Positive Supply Current	I_{DD}	5			μA typ	Digital inputs = 0 V or 3.3 V
			10	10	μA max	

[1] Guaranteed by design; not subject to production test.

±2.5 V DUAL SUPPLY

V_{DD} = +2.5 V ± 10%, V_{SS} = −2.5 V ± 10%, GND = 0 V, unless otherwise noted.

Table 3.

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range			V_{SS} to V_{DD}		V	
On Resistance	R_{ON}	4			Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA, see Figure 18
		5.5	6	7	Ω max	
On Resistance Match Between Channels	ΔR_{ON}		0.3		Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA
			0.8	1	Ω max	
On Resistance Flatness	$R_{FLAT (ON)}$	0.5			Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA
			1	1.2	Ω max	
LEAKAGE CURRENTS						V_{DD} = +2.75 V, V_{SS} = −2.75 V
Source Off Leakage	I_S (Off)	±0.01			nA typ	V_S = +2.25 V/−1.25 V, V_D = −1.25 V/+2.25 V, see Figure 19
		±0.25	±0.5	±1	nA max	
Drain Off Leakage	I_D (Off)	±0.05			nA typ	V_S = +2.25 V/−1.25 V, V_D = −1.25 V/+2.25 V, see Figure 22
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
Channel On Leakage	I_D, I_S (On)	±0.05			nA typ	V_S = V_D = +2.25 V/−1.25 V, see Figure 23
ADG726		±0.5	±2.5		nA max	
ADG732		±1	±5	±10	nA max	
DIGITAL INPUTS						
Input High Voltage	V_{INH}		1.7	1.7	V min	
Input Low Voltage	V_{INL}		0.7	0.7	V max	
Input Current						
	I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.5	±0.5	μA max	
Digital Input Capacitance	C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS[1]						
Transition Time	$t_{TRANSITION}$	33			ns typ	R_L = 300 Ω, C_L = 35 pF, see Figure 25
		45	51	56	ns max	V_{S1} = 1.5 V/0 V, V_{S32} = 0 V/1.5 V
Break-Before-Make Time Delay	t_D	15			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 1.5 V, see Figure 26
			1	1	ns min	
On Time ($\overline{CS}$, $\overline{WR}$)	t_{ON} ($\overline{WR}$, $\overline{CS}$)	21			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 1.5 V, see Figure 27
		30	37	43	ns max	
Off Time ($\overline{CS}$, $\overline{WR}$)	t_{OFF} ($\overline{WR}$, $\overline{CS}$)	20			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 1.5 V, see Figure 27
		29	35	38	ns max	
On Time ($\overline{EN}$)	t_{ON} ($\overline{EN}$)	26			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 1.8 V, see Figure 28
		37		50	ns max	
Off Time ($\overline{EN}$)	t_{OFF} ($\overline{EN}$)	18			ns typ	R_L = 300 Ω, C_L = 35 pF; V_S = 1.8 V, see Figure 28
		26	29	29	ns max	
Charge Injection	Q_{INJ}	1			pC typ	V_S = 0 V, R_S = 0 Ω, C_L = 1 nF, see Figure 29
Off Isolation	I_{SO}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 20
Channel-to-Channel Crosstalk	C_{TK}	−72			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz, see Figure 21
−3 dB Bandwidth	BW					R_L = 50 Ω, C_L = 5 pF, see Figure 24
ADG726		34			MHz typ	
ADG732		18			MHz typ	

Parameter	Symbol	ADG726/ADG732 +25°C	ADG726/ADG732 −40°C to +85°C	ADG732 −40°C to +125°C	Unit	Test Conditions/Comments
Off Switch Source Capacitance	C_S (Off)	13			pF typ	
Off Switch Drain Capacitance	C_D (Off)					
ADG726		137			pF typ	f = 1 MHz
ADG732		275			pF typ	f = 1 MHz
On Switch Drain, Source Capacitance	C_D, C_S (On)					
ADG726		150			pF typ	f = 1 MHz
ADG732		300			pF typ	f = 1 MHz
POWER REQUIREMENTS						
Positive Supply Current	I_{DD}	10			µA typ	V_{DD} = 2.75 V
			20	20	µA max	Digital inputs = 0 V or 2.75 V
Negative Supply Current	I_{SS}	10			µA typ	V_{DD} = −2.75 V
			20	20	µA max	Digital inputs = 0 V or 2.75 V

[1] Guaranteed by design; not subject to production test.

TIMING CHARACTERISTICS

Table 4.

Parameter[1, 2, 3]	Limit at T_{MIN}, T_{MAX}	Unit	Test Conditions/Comments
t_1	0	ns min	$\overline{CS}$ to $\overline{WR}$ setup time
t_2	0	ns min	$\overline{CS}$ to $\overline{WR}$ hold time
t_3	10	ns min	$\overline{WR}$ pulse width
t_4	10	ns min	Time between $\overline{WR}$ cycles
t_5	5	ns min	Address, enable setup time
t_6	2	ns min	Address, enable hold time

[1] See Figure 3.
[2] All input signals are specified with tr = tf = 1 ns (10% to 90% of V_{DD}).
[3] Guaranteed by design and characterization, not production tested.

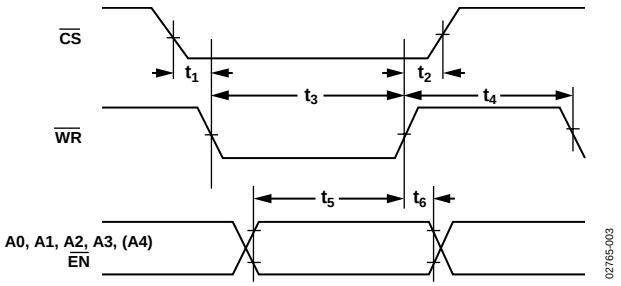


Figure 3. Timing Diagram

Figure 3 shows the timing sequence for latching the switch address and enable inputs. The latches are level sensitive; therefore, while $\overline{WR}$ is held low, the latches are transparent and the switches respond to changing the address and enable the inputs.

Input data is latched on the rising edge of $\overline{WR}$. The ADG726 has two $\overline{CS}$ inputs. This enables the device to be used either as a dual 16-to-1 channel multiplexer or a differential 16-channel multiplexer. If a differential output is required, tie $\overline{CSA}$ and $\overline{CSB}$ together.

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 5.

Parameter	Rating
V_{DD} to V_{SS}	7 V
V_{DD} to GND	−0.3 V to +7 V
V_{SS} to GND	+0.3 V to −7 V
Analog Inputs[1]	V_{SS} − 0.3 V to V_{DD} + 0.3 V or 30 mA, whichever occurs first
Digital Inputs[1]	−0.3 V to V_{DD} + 0.3 V or 30 mA, whichever occurs first
Peak Current, S or D (Pulsed at 1 ms, 10% Duty Cycle Maximum)	60 mA
Continuous Current, S or D	30 mA
Operating Temperature Range	
ADG726	−40°C to +85°C
ADG732	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
Thermal Impedance θ_{JA} (4-Layer Board)	
48-Lead LFCSP	25°C/W
48-Lead TQFP	54.6°C/W
Reflow Soldering Peak Temperature, Pb Free	As per JEDEC J-STD-020

[1] Overvoltages at A, $\overline{EN}$, $\overline{WR}$, $\overline{CS}$, S, or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTION

48-LEAD TQFP

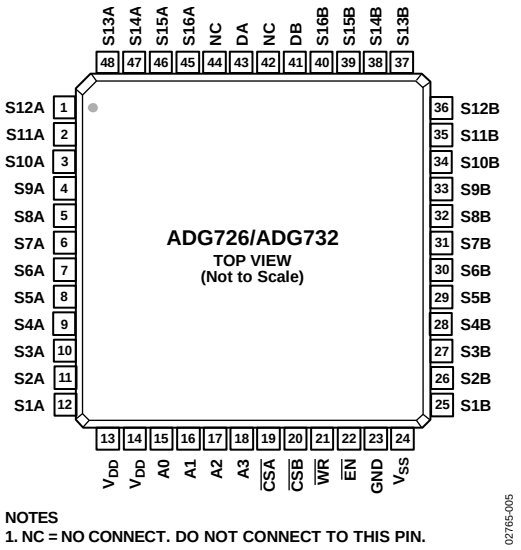


Figure 4. 48-Lead TQFP Pin Configuration

Table 6. 48-Lead TQFP Pin Function Description

Pin No.	Mnemonic	Description
1 to 12, 45 to 48	S16A to S1A	Source Terminal. This pin may be an input or output.
13, 14	V_{DD}	Most Positive Power Supply Potential.
15 to 18	A0 to A3	Logic Control Inputs.
19	$\overline{CSA}$	Chip Select Pin A. $\overline{CSA}$ is active low. If a differential output configuration is required, tie $\overline{CSA}$ and $\overline{CSB}$ together.
20	$\overline{CSB}$	Chip Select Pin B. $\overline{CSB}$ is active low. If a differential output configuration is required, tie $\overline{CSB}$ and $\overline{CSA}$ together.
21	$\overline{WR}$	Write pin. When $\overline{WR}$ is low, the logic control inputs (A0 to A3) control which state the switches are in. On the rising edge of $\overline{WR}$, the logic control input data is latched.
22	$\overline{EN}$	Active Low, Digital Input. When this pin is high, the device is disabled and all switches are off. When this pin is low, the Ax logic control inputs determine the on switches.
23	GND	Ground (0 V) Reference.
24	V_{SS}	Most Negative Power Supply in a Dual-Supply Application. In single-supply applications, connect this pin to GND.
25 to 40	S1B to S16B	Source Terminal. This pin may be an input or output.
41	DB	Drain Terminal. This pin may be an input or output.
42, 44	NC	No Connect. Do not connect to this pin.
43	DA	Drain Terminal. This pin may be an input or output.

48-LEAD LFCSP

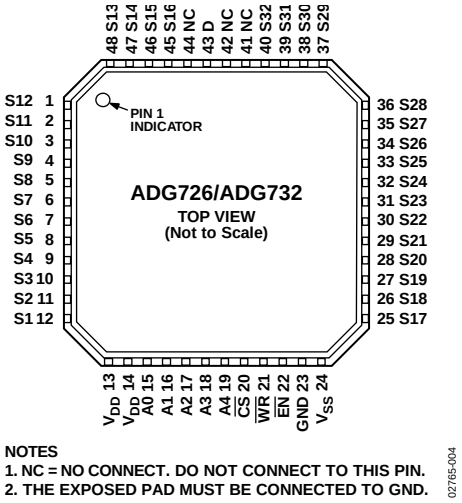


Figure 5. 48-Lead LFCSP Pin Configuration

Table 7. 48-Lead LFCSP Pin Function Description

Pin No.	Mnemonic	Description
1 to 12, 45 to 48	S16 to S1	Source Terminal. This pin may be an input or output.
13, 14	V_{DD}	Most Positive Power Supply Potential.
15 to 19	A0 to A4	Logic Control Inputs.
20	$\overline{CS}$	Chip Select Pin. $\overline{CS}$ is active low.
21	$\overline{WR}$	Write Pin. When $\overline{WR}$ is low, the logic control inputs (A0 to A4) control which state the switches are in. On the rising edge of $\overline{WR}$, the logic control input data is latched.
22	$\overline{EN}$	Active Low, Digital Input. When this pin is high, the device is disabled and all switches are off. When this pin is low, the Ax logic control inputs determine the on switches.
23	GND	Ground (0 V) Reference.
24	V_{SS}	Most Negative Power Supply in a Dual-Supply Application. In single-supply applications, connect this pin to GND.
25 to 40	S17 to S32	Source Terminal. This pin may be an input or output.
41, 42, 44	NC	No Connect. Do not connect to this pin.
43	D	Drain Terminal. This pin may be an input or output.
	EPAD	Exposed Pad. The exposed pad must be connected to GND.

Truth Tables

Table 8. ADG726 Truth Table

A3[1]	A2[1]	A1[1]	A0[1]	$\overline{EN}$[1]	$\overline{CSA}$	$\overline{CSB}$	$\overline{WR}$[1]	On Switch
X	X	X	X	X	1	1	L → H	Retains previous switch condition
X	X	X	X	X	1	1	X	No change in switch condition
X	X	X	X	1	0	0	0	None
0	0	0	0	0	0	0	0	S1A to DA, S1B to DB
0	0	0	1	0	0	0	0	S2A to DA, S2B to DB
0	0	1	0	0	0	0	0	S3A to DA, S3B to DB
0	0	1	1	0	0	0	0	S4A to DA, S4B to DB
0	1	0	0	0	0	0	0	S5A to DA, S5B to DB
0	1	0	1	0	0	0	0	S6A to DA, S6B to DB
0	1	1	0	0	0	0	0	S7A to DA, S7B to DB
0	1	1	1	0	0	0	0	S8A to DA, S8B to DB
1	0	0	0	0	0	0	0	S9A to DA, S9B to DB

A3[1]	A2[1]	A1[1]	A0[1]	$\overline{EN}$[1]	$\overline{CSA}$	$\overline{CSB}$	$\overline{WR}$[1]	On Switch
1	0	0	1	0	0	0	0	S10A to DA, S10B to DB
1	0	1	0	0	0	0	0	S11A to DA, S11B to DB
1	0	1	1	0	0	0	0	S12A to DA, S12B to DB
1	1	0	0	0	0	0	0	S13A to DA, S13B to DB
1	1	0	1	0	0	0	0	S14A to DA, S14B to DB
1	1	1	0	0	0	0	0	S15A to DA, S15B to DB
1	1	1	1	0	0	0	0	S16A to DA, S16B to DB

[1] X is don't care, L is low, and H is high.

Table 9. ADG732 Truth Table

A4[1]	A3[1]	A2[1]	A1[1]	A0[1]	$\overline{EN}$[1]	$\overline{CS}$	$\overline{WR}$[1]	Switch Condition
X	X	X	X	X	X	1	L → H	Retains previous switch condition
X	X	X	X	X	X	1	X	No change in switch condition
X	X	X	X	X	1	0	0	None
0	0	0	0	0	0	0	0	1
0	0	0	0	1	0	0	0	2
0	0	0	1	0	0	0	0	3
0	0	0	1	1	0	0	0	4
0	0	1	0	0	0	0	0	5
0	0	1	0	1	0	0	0	6
0	0	1	1	0	0	0	0	7
0	0	1	1	1	0	0	0	8
0	1	0	0	0	0	0	0	9
0	1	0	0	1	0	0	0	10
0	1	0	1	0	0	0	0	11
0	1	0	1	1	0	0	0	12
0	1	1	0	0	0	0	0	13
0	1	1	0	1	0	0	0	14
0	1	1	1	0	0	0	0	15
0	1	1	1	1	0	0	0	16
1	0	0	0	0	0	0	0	17
1	0	0	0	1	0	0	0	18
1	0	0	1	0	0	0	0	19
1	0	0	1	1	0	0	0	20
1	0	1	0	0	0	0	0	21
1	0	1	0	1	0	0	0	22
1	0	1	1	0	0	0	0	23
1	0	1	1	1	0	0	0	24
1	1	0	0	0	0	0	0	25
1	1	0	0	1	0	0	0	26
1	1	0	1	0	0	0	0	27
1	1	0	1	1	0	0	0	28
1	1	1	0	0	0	0	0	29
1	1	1	0	1	0	0	0	30
1	1	1	1	0	0	0	0	31
1	1	1	1	1	0	0	0	32

[1] X is don't care, L is low, and H is high.

TYPICAL PERFORMANCE CHARACTERISTICS

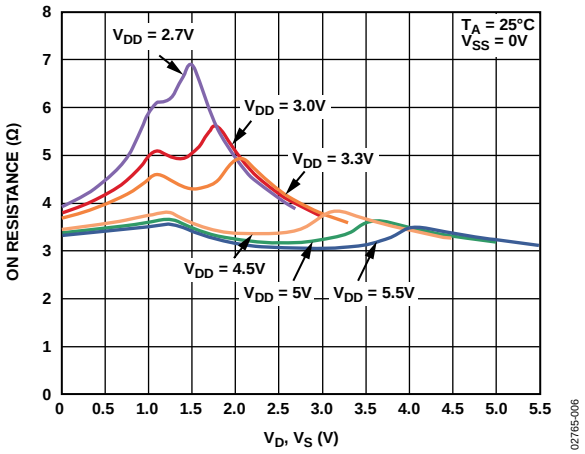


Figure 6. On Resistance vs. V_D (V_S), Single Supply

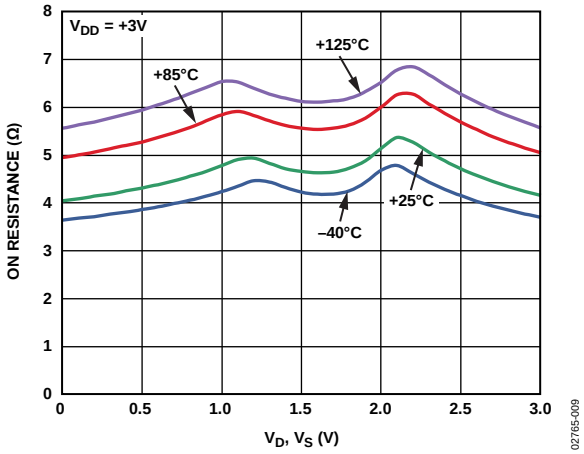


Figure 9. On Resistance vs. V_D (V_S), Single Supply

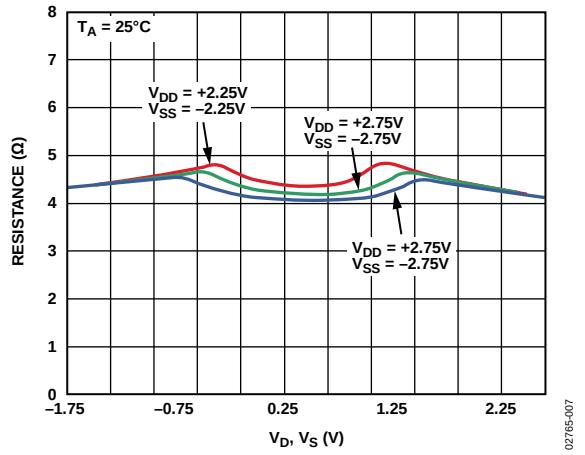


Figure 7. On Resistance vs. V_D (V_S), Dual Supply

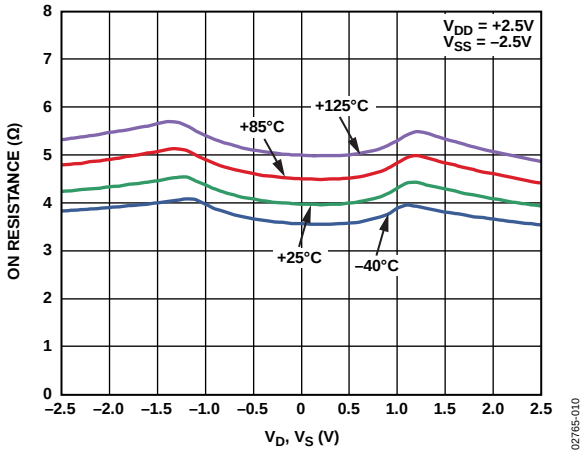


Figure 10. On Resistance vs. V_D (V_S), Dual Supply

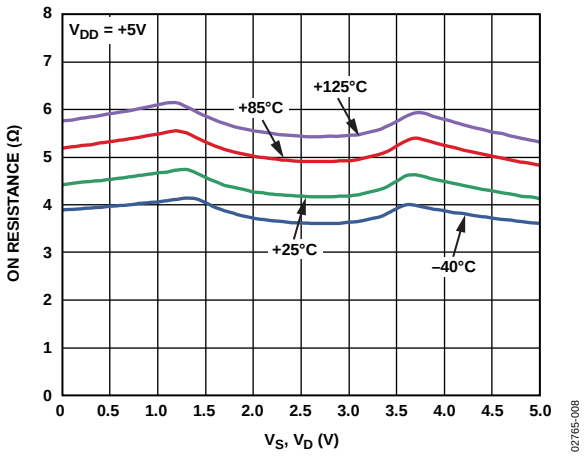


Figure 8. On Resistance vs. V_D (V_S) for Different Temperatures, Single Supply

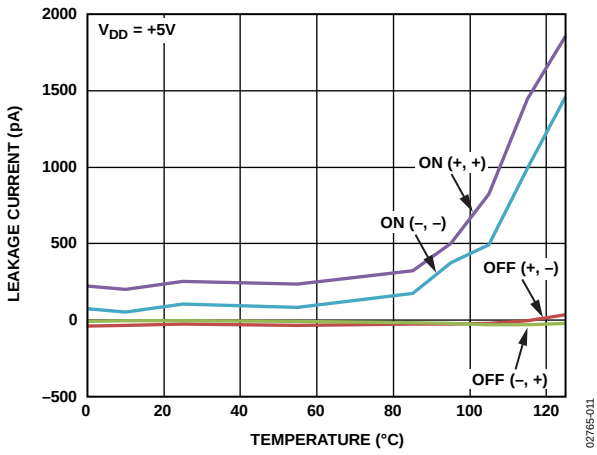


Figure 11. Leakage Currents vs. Temperature

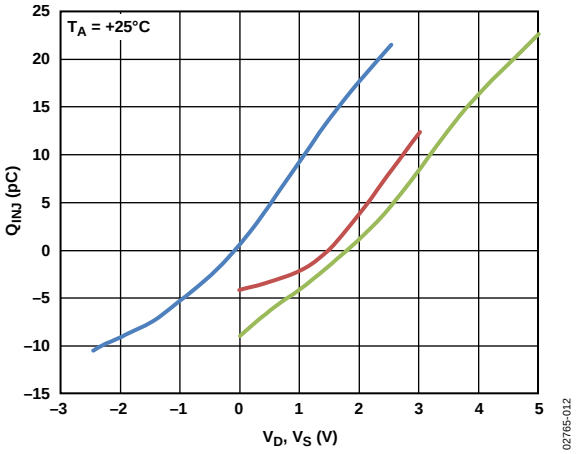


Figure 12. ADG732 Charge Injection (Q_{INJ}) vs. V_D (V_S)

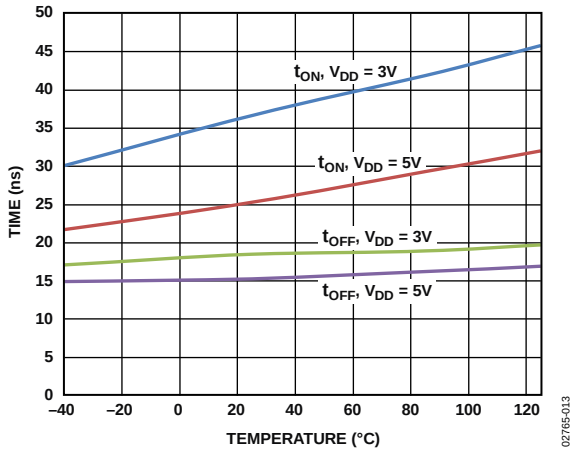


Figure 13. t_{ON}/t_{OFF} ($\overline{EN}$) Time vs. Temperature

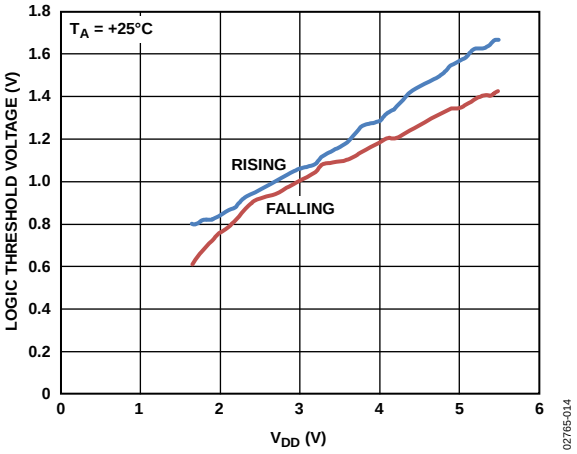


Figure 14. Logic Threshold Voltage vs. Supply Voltage (V_{DD})

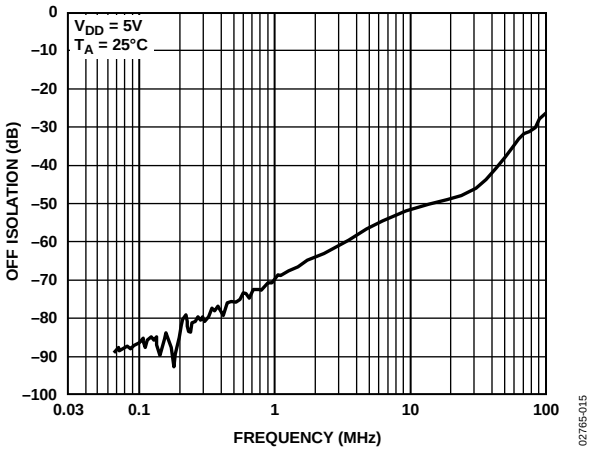


Figure 15. Off Isolation vs. Frequency

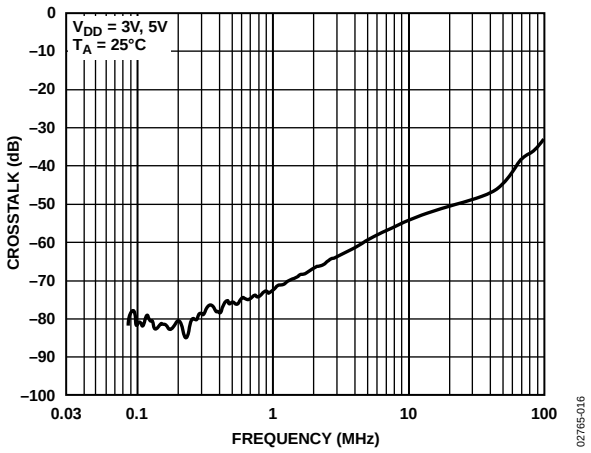


Figure 16. Crosstalk vs. Frequency

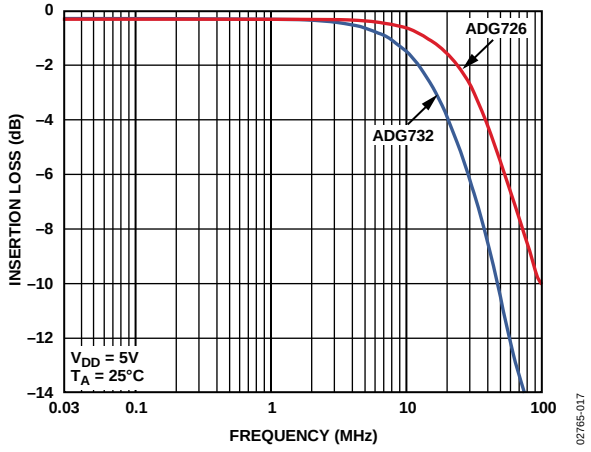


Figure 17. Insertion Loss vs. Frequency

TEST CIRCUITS

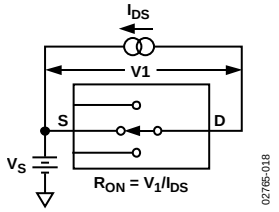


Figure 18. On Resistance

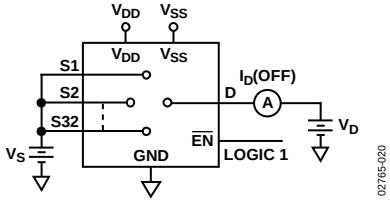


Figure 22. I_D (Off)

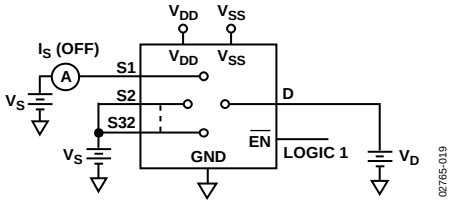


Figure 19. I_S (Off)

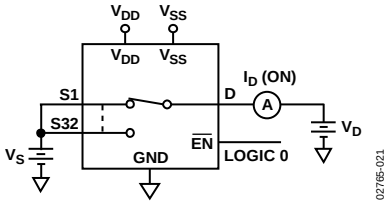


Figure 23. I_D (On)

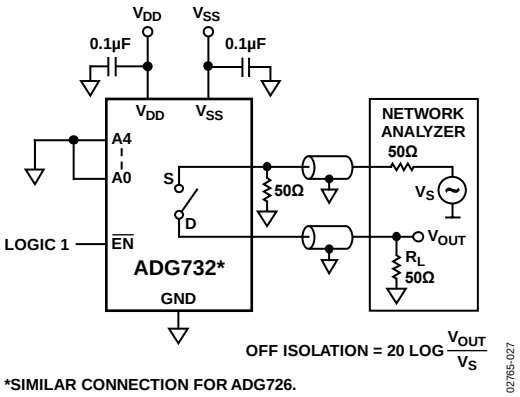


Figure 20. Off Isolation

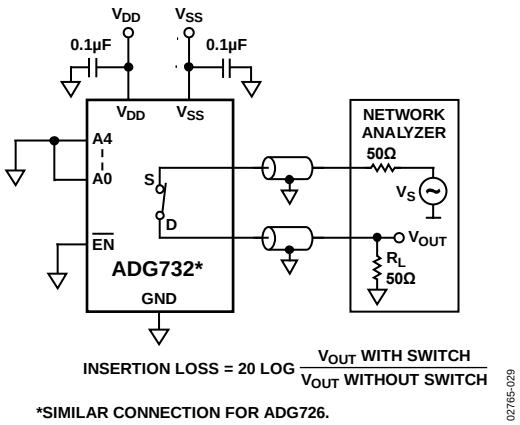


Figure 24. Bandwidth

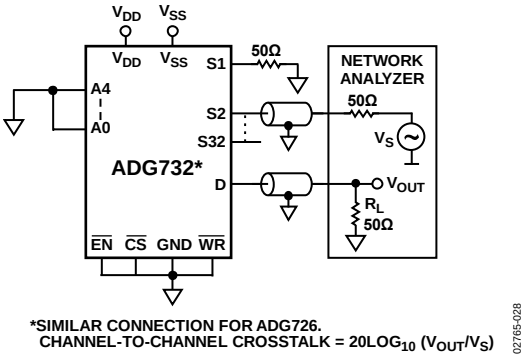


Figure 21. Channel-to-Channel Crosstalk

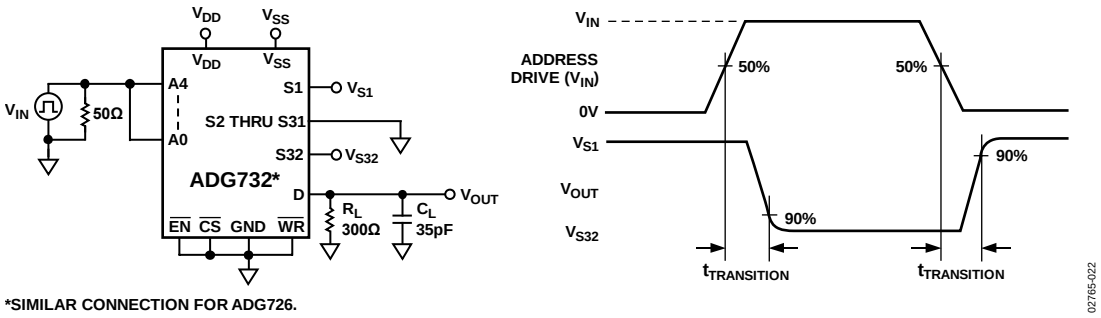


Figure 25. Switching Time of Multiplexer, $t_{TRANSITION}$

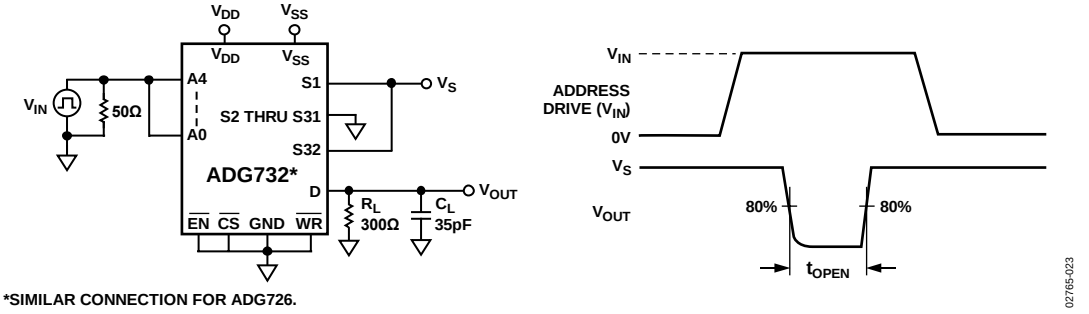


Figure 26. Break-Before-Make Delay, t_{OPEN}

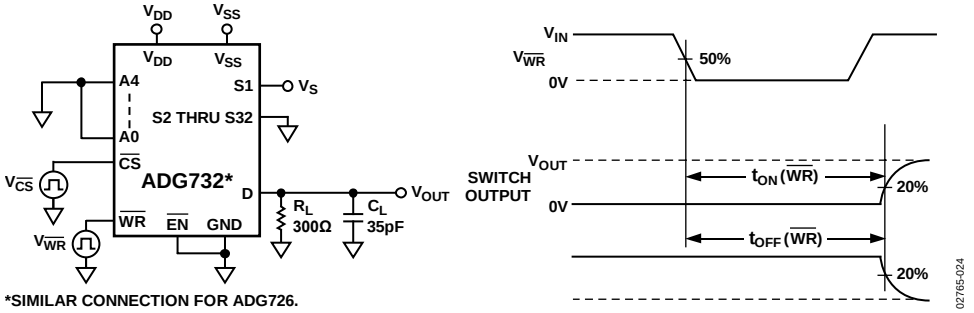


Figure 27. Write Turn-On and Turn-Off Time, t_{ON}, t_{OFF} ($\overline{WR}$)

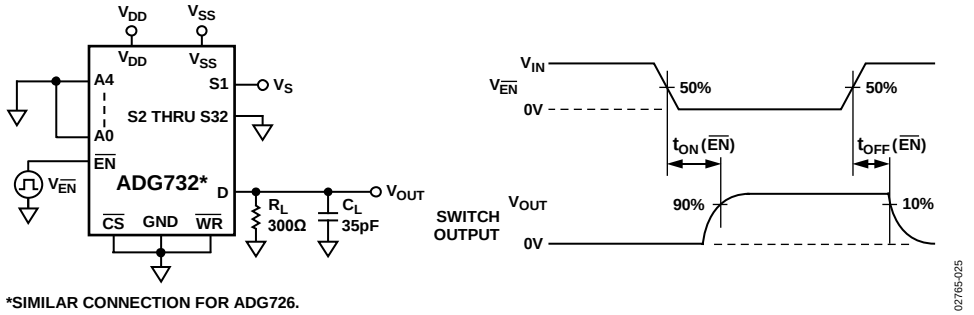


Figure 28. Enable Delay, t_{ON} ($\overline{EN}$), t_{OFF} ($\overline{EN}$)

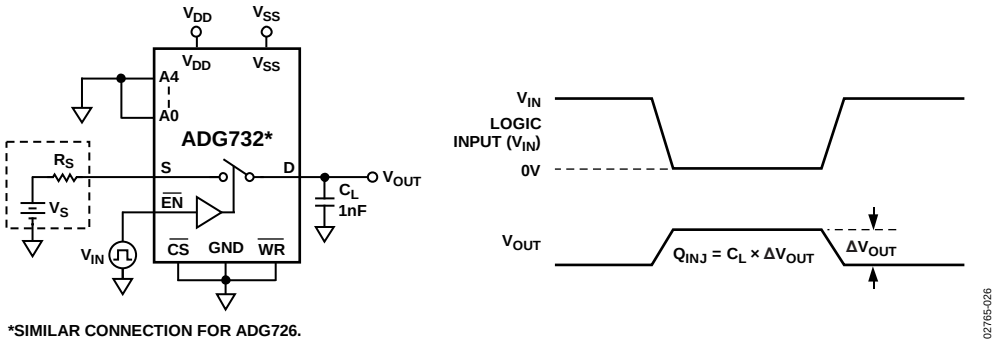


Figure 29. Charge Injection

TERMINOLOGY

I_{DD}
I_{DD} represents the positive supply current.

I_{SS}
I_{SS} represents the negative supply current.

IN
IN represents the logic control input.

V_D (V_S)
V_D and V_S represent the analog voltage on the Dx pins and the Sx pins, respectively.

R_{ON}
R_{ON} represents the ohmic resistance between the Dx pins and the Sx pins.

ΔR_{ON}
ΔR_{ON} represents the difference between the R_{ON} of any two channels.

$R_{FLAT(ON)}$
$R_{FLAT(ON)}$ is the flatness that is defined as the difference between the maximum and minimum value of on resistance measured over the specified analog signal range.

I_S (Off)
I_S (Off) represents the source leakage current with the switch off.

I_D (Off)
I_D (Off) represents the drain leakage current with the switch off.

I_D (On), I_S (On)
I_D (On) and I_S (On) represent the channel leakage currents with the switch on.

V_{INL}
V_{INL} is the maximum input voltage for Logic 0.

V_{INH}
V_{INH} is the minimum input voltage for Logic 1.

I_{INL}, I_{INH}
I_{INL} and I_{INH} represent the low and high input currents of the digital inputs.

C_S (Off)
C_S (Off) represents the off switch source capacitance. It is measured with a reference to ground.

C_D (Off)
C_D (Off) represents the off switch drain capacitance. It is measured with reference to ground.

C_D (On), C_S (On)
C_D (On) and C_S (On) represent the on switch capacitances, which are measured with reference to ground.

C_{IN}
C_{IN} is the digital input capacitance.

$t_{TRANSITION}$
$t_{TRANSITION}$ is the delay time measured between the 50% and 90% points of the digital inputs and the switch on condition when switching from one address state to another.

t_{ON} ($\overline{EN}$)
t_{ON} ($\overline{EN}$) is the delay time between the 50% and 90% points of the $\overline{EN}$ digital input and the switch on condition.

t_{OFF} ($\overline{EN}$)
t_{OFF} ($\overline{EN}$) is the delay time between the 50% and 90% points of the $\overline{EN}$ digital input and the switch off condition.

t_{OPEN}
t_{OPEN} is the off time measured between the 80% points of both switches when switching from one address state to another

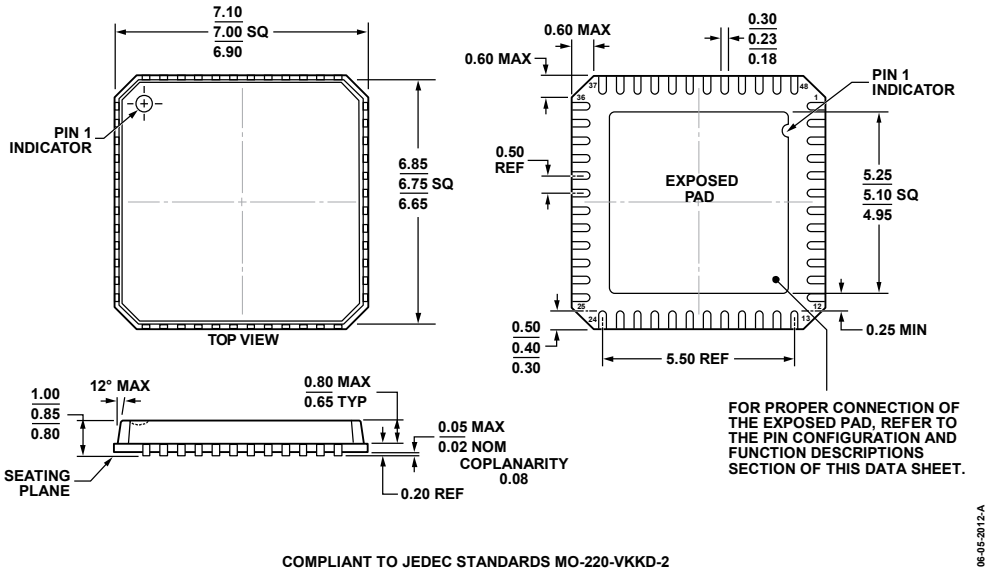
Charge Injection
Charge injection is a measure of the glitch impulse transferred from the digital input to the analog output during switching.

Off Isolation
Off isolation is a measure of the unwanted signal coupling through an off switch.

Channel-to-Channel Crosstalk
Crosstalk is a measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

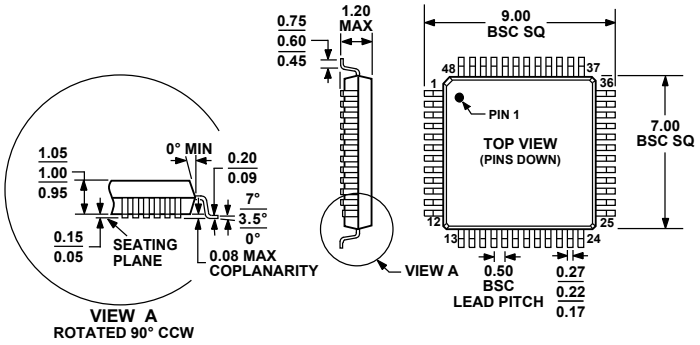
Insertion Loss
Insertion loss is the loss due to the on resistance of the switch.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-220-VKKD-2

Figure 30. 48-Lead Frame Chip Scale Package [LFCSP_VQ]
7 mm × 7 mm Body, Very Thin Quad
(CP-48-1)
Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MS-026ABC

Figure 31. 48-Lead Thin Plastic Quad Flat Package [TQFP]
(SU-48)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1]	Temperature Range	Package Description	Package Option
ADG726BCPZ	–40°C to +85°C	48-Lead Frame Chip Scale Package [LFCSP_VQ]	CP-48-1
ADG726BCPZ-REEL	–40°C to +85°C	48-Lead Frame Chip Scale Package [LFCSP_VQ]	CP-48-1
ADG726BSUZ	–40°C to +85°C	48-Lead Thin Plastic Quad Flat Package [TQFP]	SU-48
ADG726BSUZ-REEL	–40°C to +85°C	48-Lead Thin Plastic Quad Flat Package [TQFP]	SU-48
ADG732BCPZ	–40°C to +125°C	48-Lead Frame Chip Scale Package [LFCSP_VQ]	CP-48-1
ADG732BCPZ-REEL	–40°C to +125°C	48-Lead Frame Chip Scale Package [LFCSP_VQ]	CP-48-1
ADG732BSUZ	–40°C to +125°C	48-Lead Thin Plastic Quad Flat Package [TQFP]	SU-48
ADG732BSUZ-REEL	–40°C to +125°C	48-Lead Thin Plastic Quad Flat Package [TQFP]	SU-48

[1] Z = RoHS-Compliant Part